

REMARKS

The Office Action of September 21, 2004, has been carefully considered.

The specification has been amended to denote the patent number of the parent application.

Claims 6 through 9 have been rejected under 35 USC 102(b) as anticipated by Iwasaki.

Claim 6 has now been amended to more clearly define the invention. As now amended Claim 6 is directed to a method for manufacturing a light emitting diode device in which a body assembly is divided into a plurality of LED device areas formed by pressing a metal plate, with a recess formed in each of the LED areas. Slits are formed arranged on predetermined lines with the exception of the side edges, such that each of the areas is divided into a first half body and a second half body. Then, a resin is charged into each slit so as to insulate the first half body from the second half body in each area and an LED is mounted on the first and second half bodies at the bottom of each recess by bumps over the resin in the slit. A sealing resin is charged under the LED, a transparent sealing plate is secured on the body assembly, and each area is divided from the body assembly.

The invention enables the formation of a plurality of light emitting diode devices, each of which has a simple construction and a small structure because the resin does not expand and contract as in the prior art.

The Iwasaki reference discloses the formation of an exposure unit 20 comprising a metal substrate 1, three LEDs 7, 8 and 9 each mounted in a recess 4, an insulation layer 2 on the substrate 1, lead pattern 3 on the insulation layer 2, sealing material 11, mask 13 and a mask holding member 14 secured in the positioning hole 15 formed in the substrate 1.

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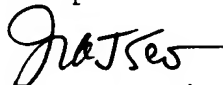
This exposure unit 20 exposes images on the recording medium 37 scanning along exposure unit 20.

The cited reference does not disclose the method of the claimed invention. Specifically, there is not disclosed the steps of preparing a body assembly having a plurality of LED device areas formed by pressing a metal plate, forming slits in these areas along a predetermined line such that each area is divided into a first half body and a second half body, charging a resin into each slit to insulate the half bodies, mounting an LED on the first and second half bodies at the bottom of the recess by bumps over the resin in the slit and dividing each area from the body assembly. While the Office action notes that resin is charged into each indentation (col. 9, lines 34-36, col. 10, lines 1-5, and Figure 1), the resin covers the LEDs, which is not the case according to the claimed invention in which the sealing resin is charged under the LEDs.

Accordingly, the reference does not disclose or suggest the invention as presently claimed, and withdrawal of this rejection is requested.

In view of the foregoing amendments and remarks, Applicants submit that the present application is now in condition for allowance. An early allowance of the application with amended claims is earnestly solicited.

Respectfully submitted,



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